



PATENTS

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Manabu MIZUSAKI

Serial No. 09/847,370

GROUP 2827

Filed May 3, 2001

Examiner James M. Mitchell

ELECTRODE STRUCTURE OF A
CARRIER SUBSTRATE OF A SEMI-
CONDUCTOR DEVICE

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of January 16, 2002,
please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 7, replace the paragraph, beginning on line 7, as
follows:

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--Then, these are thrown into a reflow furnace for
soldering, printed solder 203 is melted, and the solder 203
becomes wet and starts spreading over the soldering land 202 of
the main substrate 201 and the soldering land 103 of the BGA and
the CSP. Air stagnates in the recess of the soldering land 103
of the BGA and the CSP, and usually the air prevents the solder
203 from invading into the recess. However, in the first
embodiment of the present invention, since the air inside the
recess escapes via the slits 104 shown in FIG. 1, it becomes
possible for the solder 203 to become wet and spread in the
recess fully. When they are taken out from the reflow furnace,

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